



THIS DRAWING IS INTENDED TO HELP IN THE ASSEMBLY OF THE DESIGN.

1. REFER TO ODB++ FILE FOR SPECIFIC COMPONENT LOCATION INFORMATION.
2. REMOVE THE METAL TAB ON THE BANANA JACKS BEFORE MOUNTING THEM ON THE BOARD. USE LOCTITE THREADLOCKER BLUE 242 (OR EQUIVALENT) WHEN INSTALLING THE BANANA JACKS.
3. MOUNT THE RF FENCE ON THE TOP OF THE PCB AFTER BOARD ASSEMBLY. SOLDER THE FENCE DOWN TO THE BOARD AROUND THE EDGES. NO GAPS. PLACE THE COVER ON THE FENCE.
4. USE WATER SOLUBLE FLUX DURING BOARD ASSEMBLY. RHS COMPLIANT AND LEAD FREE ASSEMBLY.

REVISIONS			
ZONE	LTR	DESCRIPTION	DATE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE FRACTIONS DECIMALS ANGLES ±.000 ±.005 ±.01	CONTRACT NO.	TEXAS INSTRUMENTS INC.	
	APPROVALS	DATE	ASSEMBLY DRAWING
MATERIAL	ENGR M. SUDBORD	12-09-11	TSW1265
SEE NOTE 5			
FINISH	SEE NOTES 7, 8, 9		
DO NOT SCALE DRAWING		SCALE NONE	REV. A

SIZE	CODE	IDENT NO.	DRAWING NO.	REV.
D				A
SCALE	NONE			SHEET 1 OF 1

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